# Engineered Materials Product Finder

**INDIUM CORPORATION®**

| | |
|---|---|
| Date | |
| Sales Channel Partner | |

**Attach Customer Business Card Here (if available)**

| | |
|---|---|
| Name | |
| Tel/Mob | |
| Email | |
| Company Name | |

## 1. Vertical

- ☐ IGBT
- ☐ LED
- ☐ RF
- ☐ PCBA - Fortification
- ☐ Automotive
- ☐ Microwave
- ☐ Medical
- ☐ Other
- ☐ Laser
- ☐ Solar
- ☐ Military/Aero

**Describe Other:**

## 2. What is the solder's function?

☐ Thermal with Reflow   ☐ Thermal No Reflow - Compression Force   ☐ Mechanical   ☐ Sealing   ☐ Electrical

## 3. Describe the Application

| | | Substrate Metallisation | Thickness | Unit |
|---|---|---|---|---|
| Picture/Drawing of the Application? ☐ Yes ☐ No | *Example:* | | | |
| Min Operating Temp. ℃ | | | | |
| Max Operating Temp. ℃ | **Nickel 5µm** | | | |
| Reliability Requirements: | **Gold 0.005µm** | | | |
| ☐ Thermal Cycling | Solder Alloy | | | |
| ☐ Drop/Shock | **Gold 0.005µm** | | | |
| ☐ Other | **Palladium 0.005µm** | | | |
| Describe Other: | **Nickel 3–6µ** | | | |

## 4. Describe the Current Soldering Process

| | | | |
|---|---|---|---|
| Max Soldering Process Temp. (℃) | Alloy Melting Point (℃) | Alloy Composition | |

Equipment: ☐ Convection Oven ☐ Vacuum Oven ☐ Vapour Phase ☐ Hotplate ☐ Soldering Iron ☐ Hot Air Gun ☐ Other

Atmosphere: ☐ Air ☐ $N_2$ [$O_2$ ppm - ] ☐ Vacuum ☐ Forming Gas ☐ Formic Acid ☐ Argon

Flux Used: ☐ Yes ☐ No   Flux Type: ☐ Flux-Coated Preforms ☐ Tacky Flux ☐ Liquid Flux ☐ No-Clean ☐ Water Wash

## 5. Preforms

| Indalloy® # | Preform Drawing Attached? with dimensions ☐ Yes ☐ No | Preform Dimensions ☐ mm ☐ inches |
|---|---|---|

| ☐ Wire | ☐ Ribbon | ☐ Disc | ☐ Washer | ☐ Foil/Square/Rectangle | ☐ Frame | ☐ Heat-Spring® |
|---|---|---|---|---|---|---|
| | | | | | | |
| | | | | | | |
| | | | | | | |
| | | | | | | |
| | | | | | | |

Packaging Options: ☐ Tape & Reel ☐ Waffle ☐ Tray Bulk ☐ Tray Pocket ☐ Bundle ☐ Bulk Pack

| Flux Coating | @ | % |
|---|---|---|
| Volumes: | /year | /month | / |

## 6. Other Requirements

Special Cleanliness Specifications?

Special Packaging Requirements?

Other Special Requirements?

## 7. Project Time Frame

Time Frame: ☐ Proof of Concept ☐ Ramp-up Mode ☐ Est. time to HVM? ☐ Process Improvement

*Please make additional notes on next page*

Form No. 98838 (A4) R0

**Additional Notes:**

## From One Engineer to Another®

**www.indium.com**          **askus@indium.com**

ASIA:      Singapore, Cheongju: +65 6268 8678
CHINA:    Suzhou, Shenzhen, Liuzhou: +86 (0)512 628 34900
EUROPE: Milton Keynes, Torino: +44 (0) 1908 580400
USA:       Utica, Clinton, Chicago: +1 315 853 4900

**INDIUM**
**CORPORATION®**